



PCN-20200327 TE0808-04 to TE0808-05 Hardware Revision Change

Revision v.7

Exported on 2020-04-08

Online version of this document:

<https://wiki.trenz-electronic.de/display/PD/PCN-20200327+TE0808-04+to+TE0808-05+Hardware+Revision+Change>

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Company	Trenz Electronic GmbH
PCN Number	PCN-20200327
Title	TE0808-04 to TE0808-05 Hardware Revision Change
Subject	Hardware Revision Change
Issue Date	2020-04-08

4 Products Affected

This change affects all Trenz Electronic TE0808 SoMs of revision 04: TE0808-04-*

Revision 04 is still continued. See Production Shipment Schedule below for further details.

Affected Product	Replacement
TE0808-04-*	TE0808-05-*

5 Changes

5.1 #1 Revised PL_VCCINT power supply.

Type: PCB change

Reason: Improve design for higher core utilization.

Impact: Up to 30 A PL core current possible.

5.2 #2 Added signal BG1, revised routing and placement of DDR4

Type: Schematic change

Reason: Add support of new packages of DDP DDR4 ICs.

Impact: DDP DDR4 now supported.

5.3 #3 R5 value changed to 49.9 Ohm and connected to VCCO

Type: Schematic change

Reason: Xilinx recommendation UG583.

Impact: R5 pulled up to VCCO_PSDDR.

5.4 #4 Added test points

Type: Schematic change

Reason: Improve factory testability.

Impact: Automatic testing possible.

5.5 #5 Added MAC EEPROM U4 and I²C pullups

Type: Schematic change

Reason: Improve interchangeability with TE0803 series.

Impact: User EEPROM accessible via PLL I²C bus.

5.6 #6 Revised FPGA location

Type: PCB change

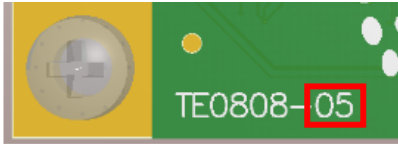
Reason: Improve Layout and support for small BGA cooler with BGA frame clips.

Impact: Package placed 1.5 mm closer to connector J3.

Note: Due to the changes above the height profile of the module is changed. Using TE0808-05 board as a replacement or in system designed for TE0808-04, review and adaption of mechanics e.g. cooling solutions have to be done.

6 Method of Identification

The revision number is printed in the top side of the PCB.



7 Production Shipment Schedule

The new revision 05 is available from Juli 2020. Revision 04 is still continued. For new designs revision 05 should be used. It is recommended to switch to the new revision when possible.

8 Contact Information

If you have any questions related to this PCN, please contact Trenz Electronics Technical Support at

- forum.trenz-electronic.de¹
- wiki.trenz-electronic.de²
- support@trenz-electronic.de³ (subject = PCN-20200327)
- phone
 - national calls: 05741 3200-0
 - international calls: 0049 5741 3200-0

¹ <http://forum.trenz-electronic.de/>

² <http://wiki.trenz-electronic.de/>

³ <mailto:support@trenz-electronic.de?subject=PCN-20140730>

9 Disclaimer

Any projected dates in this PCN are based on the most current product information at the time this PCN is being issued, but they may change due to unforeseen circumstances. For the latest schedule and any other information, please contact your local Trenz Electronic sales office, technical support or local distributor.

This PCN follows JEDEC Standard J-STD-046.